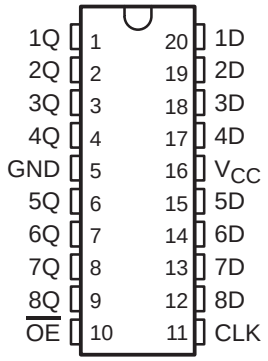
- **3-State Outputs Drive Bus Lines Directly**
- **Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (N) 300-mil DIPs**

DW OR N PACKAGE
(TOP VIEW)



description

This 8-bit flip-flop features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight flip-flops of the SN74AS4374B are edge-triggered D-type flip-flops. On the second positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

The output-enable ($\overline{OE}$) input does not affect internal operations of the flip-flops. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN74AS4374B is characterized for operation from 0°C to 70°C.

FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT
$\overline{OE}$	CLK	D†	Q
H	X	X	Z
L	↑	L	L
L	↑	H	H
L	L	X	Q_0

† Data presented at the D inputs require two clock cycles to appear at the Q outputs.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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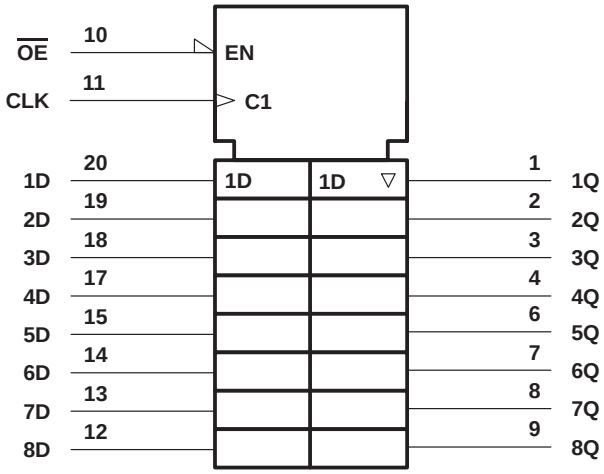
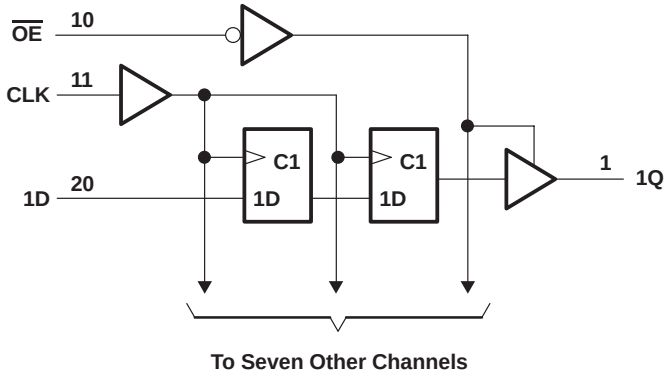
logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC} . . . . . 7 V
Input voltage, V_I . . . . . 5.5 V
Voltage applied to any output in the high state or power-off state, V_O . . . . . 5.5 V
Operating free-air temperature range, T_A . . . . . 0°C to 70°C
Storage temperature range . . . . . –65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{OH}	High-level output current			–15	mA
I_{OL}	Low-level output current			48	mA
T_A	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA			–1.5	V
V_{OH}	V_{CC} = 4.5 V	I_{OH} = –3 mA	2.4	3.2		V
		I_{OH} = –15 mA	2			
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 32 mA		0.25	0.4	V
		I_{OL} = 48 mA		0.35	0.5	
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V			20	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.4 V			–20	µA
I_I	V_{CC} = 5.5 V,	V_I = 7 V			0.1	mA
I_{IH}	V_{CC} = 5.5 V,	V_I = 2.7 V			20	µA
I_{IL}	V_{CC} = 5.5 V,	V_I = 0.5 V			–0.2	mA
I_O‡	V_{CC} = 5.5 V,	V_O = 2.25 V	–30		–112	mA
I_{CC}	V_{CC} = 5.5 V,	$\overline{OE}$ high		100	150	mA

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

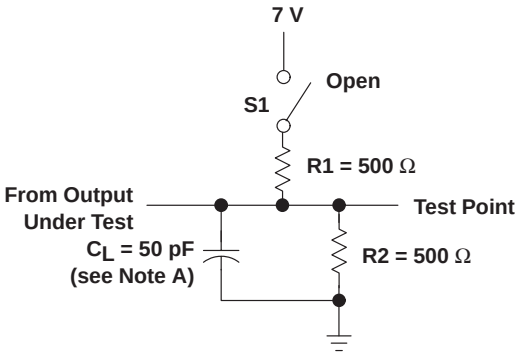
		MIN	MAX	UNIT
f_{clock}	Clock frequency	0	125	MHz
t_w	Pulse duration, CLK high or low	4		ns
t_{su}	Setup time, data before CLK↑	4		ns
t_h	Hold time, data after CLK↑	1		ns

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX§		UNIT
			MIN	MAX	
f_{max}			125		MHz
t_{PLH}	CLK	Q	2	8	ns
t_{PHL}			2	8	
t_{PZH}	$\overline{OE}$	Q	1.5	6	ns
t_{PZL}			2.5	8	
t_{PHZ}	$\overline{OE}$	Q	2	6.5	ns
t_{PLZ}			2.5	7	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

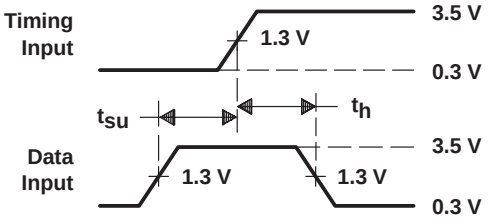
PARAMETER MEASUREMENT INFORMATION



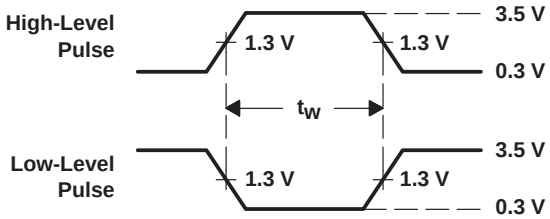
LOAD CIRCUIT
FOR 3-STATE OUTPUTS

SWITCH POSITION TABLE

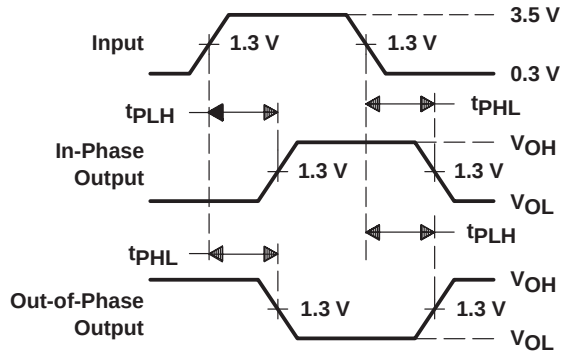
TEST	S1
t_{PLH}	Open
t_{PHL}	Open
t_{PZH}	Open
t_{PZL}	Closed
t_{PHZ}	Open
t_{PLZ}	Closed



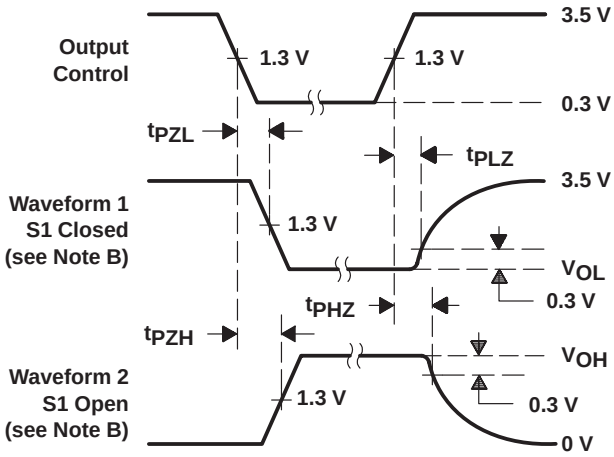
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PULSE DURATIONS



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2 ns, t_f ≤ 2 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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